

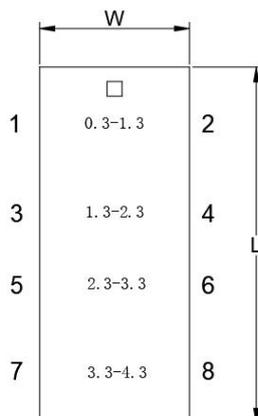
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

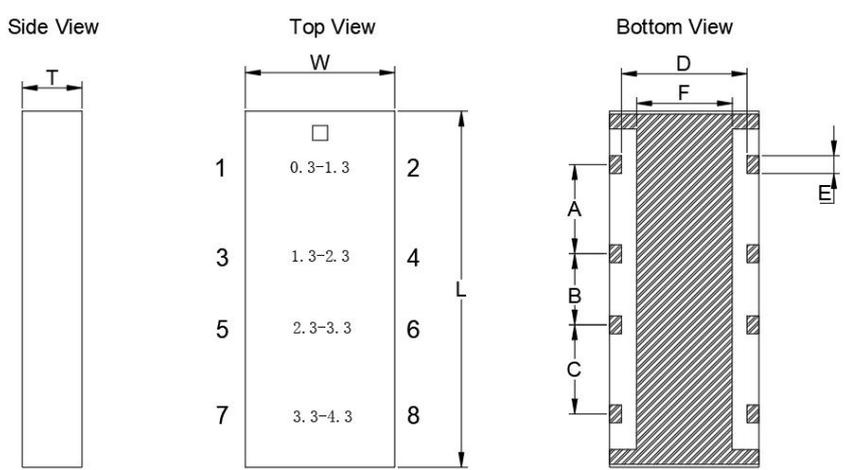
NO.	Specification				
		BPF_1	BPF_2	BPF_3	BPF_4
1	Frequency range (MHz)	300~1300	1300~2300	2300~3300	3300~4300
2	Insertion Loss (dB) @25°C	≤2	≤2.5	≤3	≤3.5
3	-1.2dB Bandwidth(MHz)	≥1000	≥1000	≥1000	≥1000
4	VSWR (In BW)	≤1.5	≤1.5	≤1.5	≤1.5
5	Attenuation(dBc)	≥40 @ DC~150 MHz	≥40 @ DC~1000 MHz	≥40 @ DC~2000 MHz	≥40 @ DC~3000 MHz
		≥40@ 1600~5000 MHz	≥40@2600~5000 MHz	≥ 40 @3600~5000 MHz	≥ 40 @4600~6000 MHz
6	Impedance (Ω)	50Ω			
<b>Operating &amp; Storage Condition (Component)</b>					
Operation Temperature Range: -40°C ~ +85°C					
Storage Temperature Range: -40°C~ +85°C					
<b>Storage Condition before Soldering (Included packaging material)</b>					
Storage Temperature Range: +5 ~ +40 °C					
Humidity: 30 to 70% relative humidity					

### Construction

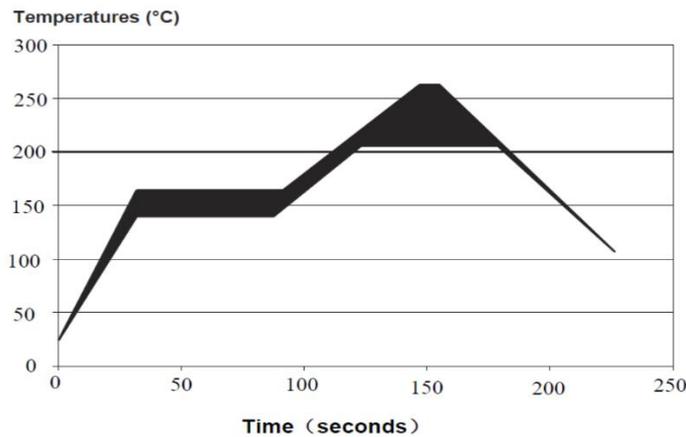


PIN	Connection	PIN	Connection
1	BPF 0.3-1.3_input Port	2	BPF 0.3-1.3_output Port
3	BPF 1.3-2.3_input Port	4	BPF 1.3-2.3_output Port
5	BPF 2.3-3.3_input Port	6	BPF 2.3-3.3_output Port
7	BPF 3.3-4.3_input Port	8	BPF 3.3-4.3_output Port

### Dimensions

Figure			Symbol	Dimension (mm)
	L	12.00 ± 0.30		
	W	5.00 ± 0.30		
	T	2.00 MAX		
	A	3.00 ± 0.15		
	B	2.40 ± 0.15		
	C	3.00 ± 0.15		
	D	4.20 ± 0.15		
	E	0.60 ± 0.15		
F	1.35 ± 0.15			

### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.